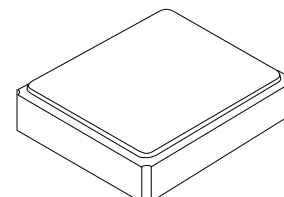




- **Temperature Compensated Crystal Oscillator**
- **Miniature 3.2 x 2.5 mm SMD Package**
- **Excellent Frequency Stability**
- **Low Phase Noise**
- **Complies with Directive 2002/95/EC (RoHS)** 

XTC7006

**26.00000 MHz
TCXO**



4-Terminal SMD Case

Electrical Characteristics

Characteristic	Sym	Notes	Minimum	Typical	Maximum	Units
Nominal Frequency	F _O			26.00000		MHz
Storage Temperature Range in Tape and Reel			-30		+85	°C
Operating Temperature Range			-30		+85	°C
Power Supply Voltage	V _{DD}		2.7	3.0	3.3	V
Output Voltage with 10 pF 10 KΩ Load	V _{OUT}		0.8			V _{P-P}
Output Waveform			Clipped Sinewave			
Power Supply Current	I _{DD}				1.5	mA
Frequency Tolerance after Reflow			±2 ppm maximum @ 25 ±3 °C			
Frequency Stability versus:						
Temperature, -30 to 85 °C					±0.5	ppm
Load Variation, 10 pF 10 KΩ ±10%					±0.2	ppm
Supply Voltage, 3.00 V ±5%					±0.2	ppm
Frequency Slope (one measurement at least every 2 °C)			±0.3 ppm/°C maximum, -30 to 80 °C			
Start Up Time, 90% of Final RF level in V _{P-P}					2.0	ms
Harmonics					-7.0	dBc
Aging at 25 °C					±1.0	ppm/yr
Phase Noise @ 1 kHz carrier offset					-130	dBc/Hz
Standard Shipping Quantity on 180 mm (7") Reel				1000		units
Lid Symbolization (in addition to Lot and/or Date Codes)	Line1: 7006 Line2: YWWS					

Pin Connections

Connection	Terminals
Ground	1
Ground	2
TCXO Output	3
V _{DD}	4



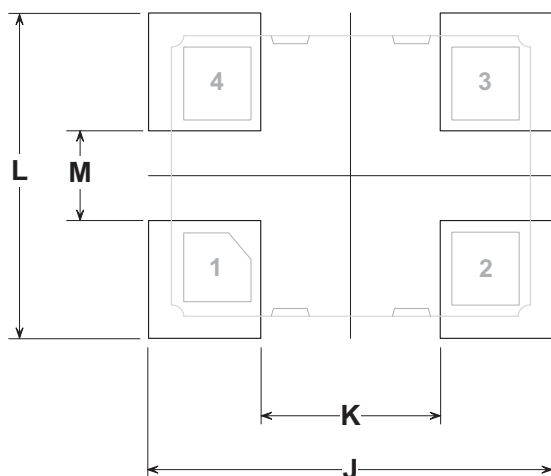
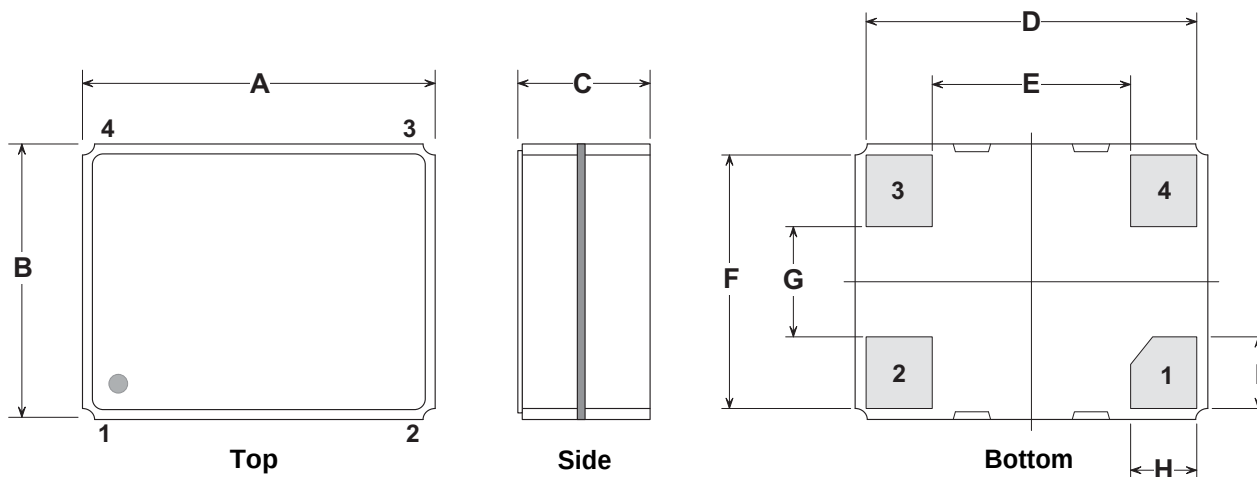
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

Notes:

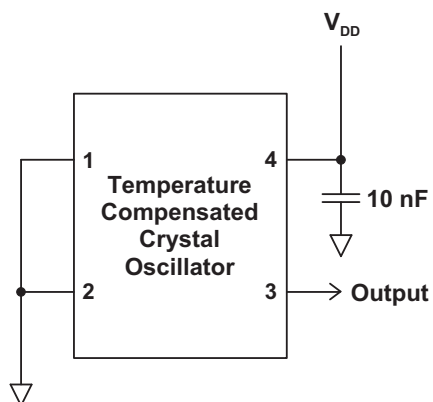
1. The design, manufacturing process, and specifications of this device are subject to change without notice.

4-Terminal Surface-Mount Seam Weld Case

3.2 x 2.5 mm Nominal Footprint



PCB Land Pattern
(Top View)



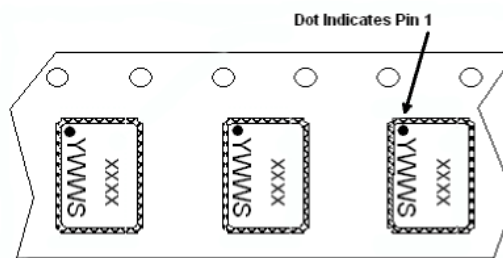
TCXO Application Circuit

Case and PCB Land Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.00	3.20	3.40	0.118	0.126	0.134
B	2.30	2.50	2.70	0.091	0.098	0.106
C	-	-	1.20	-	-	0.047
D	-	3.08	-	-	0.121	-
E	-	1.80	-	-	0.071	-
F	-	2.38	-	-	0.094	-
G	-	1.00	-	-	0.039	-
H	-	0.60	-	-	0.024	-
I	-	0.65	-	-	0.026	-
J	-	3.60	-	-	0.142	-
K	-	1.60	-	-	0.063	-
L	-	2.90	-	-	0.114	-
M	-	0.80	-	-	0.031	-

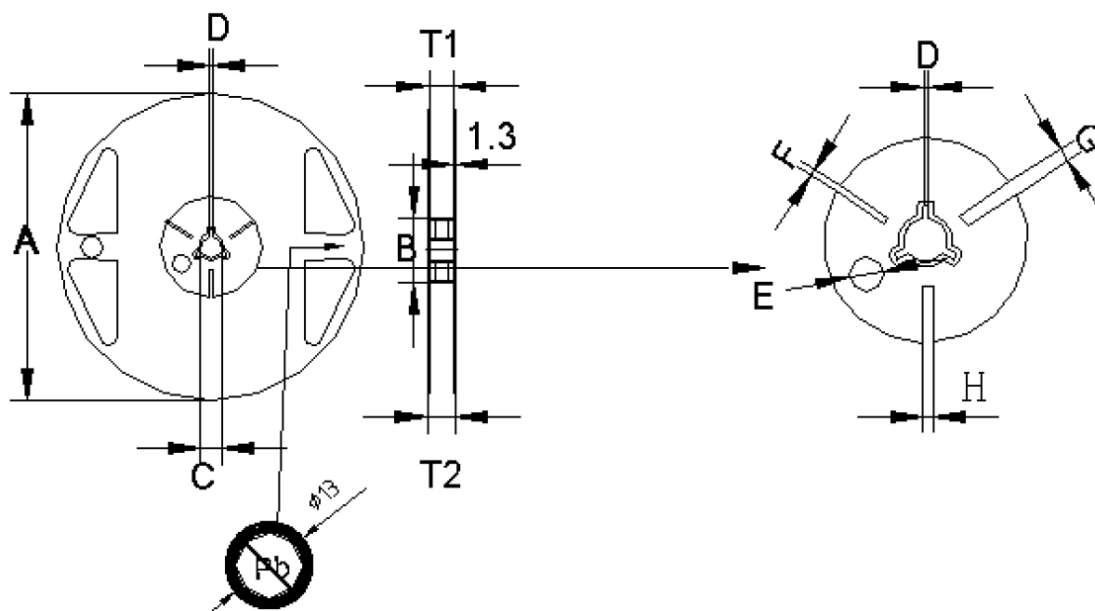
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic
Pb Free	



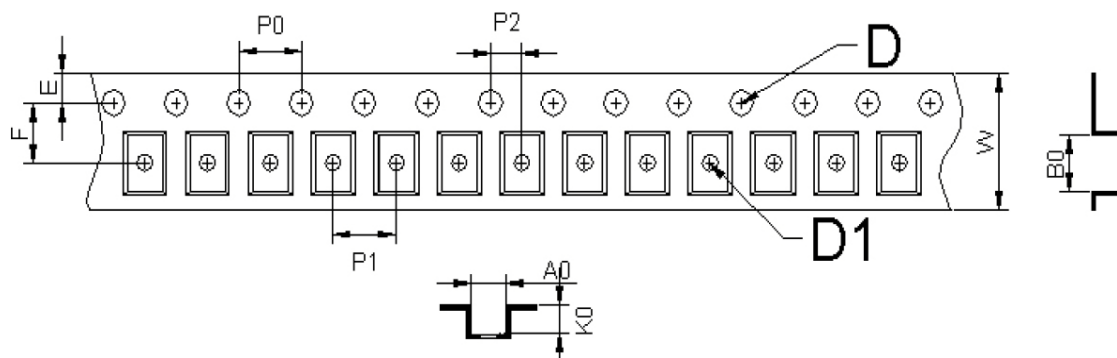
Package Orientation in Carrier Tape

Reel Dimensions



mm	A	B	C	D	E	F	G	H	T1	T2	T3
Dimension	180	60	13.0	2.0	9.1	2.9	4.9	3.9	9.0	11.4	1.2
Tolerance	±1.0	+1.0/-0.0	±0.2	±0.5	±0.5	±0.5	±0.5	±0.5	±0.3	±1.0	±0.1

Tape Dimensions



mm	A0	B0	W	F	E	P0	P1	P2	D1	D	K0	t
Dimension	2.80	3.71	8.00	3.50	1.75	4.00	4.00	2.00	1.50	1.00	1.75	0.25
Tolerance	±0.10	±0.10	+0.30/-0.10	±0.05	±0.10	±0.10	±0.10	±0.05	+0.10/-0.00	+0.25/-0.00	±0.10	±0.02

Typical Solder Reflow Profile

